
PRODUCT CHANGE NOTICE

**Alternate Manufacturing Site
for Assembly of the Listed
Intersil 8-Lead SOIC
Packaged Products**

**Refer to:
PCN12026**

Date: April 25, 2012

April 25, 2012

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of the Listed Intersil 8-Lead SOIC Packaged Products – Advanced Semiconductor Engineering - Chung-Li, Taiwan (ASECL)**

This notice is to inform you that Intersil will begin using the Advanced Semiconductor Engineering (ASECL) facility as alternate site for assembly of the listed 8-lead SOIC (Small Outline Integrated Circuit) packaged products. Products manufactured at the ASECL facility will be assembled using copper bond wire as an alternate to the gold wire currently used today. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep, and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. As of this notice, all product and site-specific qualification activities are complete.

Products affected:

ISL6612ACBZ	ISL6612ACBZA-TS2490	ISL6545CBZ-TS2568	ISL6545IBZ-TS2568
ISL6612ACBZ-T	ISL6612ACBZA-TS2490S	ISL6545CBZ-TS2694	ISL6545IBZ-TS2704
ISL6612ACBZ-TR5214	ISL6612ACBZAR5214	ISL6545CBZ-TS2698	ISL6545IBZS2704
ISL6612ACBZ-TS2568	ISL6612ACBZR5214	ISL6545CBZ-TS2704	ISL3152EIBZ
ISL6612ACBZ-TS2709	ISL6612AIBZ	ISL6545CBZS2698	ISL3152EIBZ-T
ISL6612ACBZA	ISL6612AIBZ-T	ISL6545CBZS2704	ISL3152EIBZ-T7A
ISL6612ACBZA-T	ISL6545CBZ	ISL6545IBZ	
ISL6612ACBZA-TR5214	ISL6545CBZ-T	ISL6545IBZ-T	

The Advanced Semiconductor Engineering (ASECL) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly of packaged products with both copper and gold bond wire material. There will be no change in the mold compound, die attach, lead frame material, or package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260 °C per J-STD-020). The qualified material set combinations for assembly and other key items are as follows:

Key Items	ANST Current	ASECL New (Alternate)
Mold Compound	Sumitomo EME-G600	Sumitomo EME-G600
Die Attach	Ablebond 8290	Ablebond 8290
Bond Wire	1.0 or 1.2mil Gold (Au)	1.2 mil Copper (Cu)
Moisture Sensitivity Level	1	3
Device Marking - Site Code	V	W

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ASECL may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at ASECL with copper bond wire is "W".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,



Jon Brewster
Intersil Corporation

PCN12026

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PCN12026 – ASECL Reliability Qualification Summary

Device		ISL3152EIBZ-T		
Rel Stress	Conditions	Lot #1	Lot #2	Lot #3
Bond Pull Integrity (ABI)	175C / 96 hrs	0/2	0/2	0/2
MSL	L3 Pb Free / 192 hrs	0/22	0/22	0/22
uHAST	85%RH / 130C /96 hrs L3 PbFree precond	0/80	0/80	0/80
WPT after uHAST	post uHAST	0/2	0/2	0/2
Temp Cycle	-65C to +150C / 500 cycle L3 PbFree precond	0/80	0/80	0/80
WPT after Temp Cycle	Post Temp Cycle	0/2	0/2	0/2